



2019 IEEE PELS/PMSA Phoenix Workshop on Packaging and Integration in Power Delivery (PwrPack)

- An Exploratory Discussion Leading to PwrSoC

Oct. 31- Nov. 1, 2019

Location: Skysong Innovation Synergy II, Arizona State University

This Workshop uniquely spotlights technology and manufacturing advancement of miniaturization and integration of power conversion and power management solutions.

The Power Sources Manufacturers Association (PSMA), in partnership with IEEE Power Electronics Society (PELS), is sponsoring a Phoenix Workshop on Packaging and Integration in Power Delivery at Arizona State University's SkySong Innovation in Scottsdale, AZ October 31-Nov. 1, 2019. This two half-day event is An Exploratory Workshop Leading to the [2020 International Workshop on Power Supply on Chip \(PwrSoC\)](#), in Philadelphia, PA.

In recent years power electronic devices' overall form factor have scaled-down significantly for a broad range of applications and power levels. This two-half day workshop will focus on two topics related to power delivery in a package:

1. Power system in package (PSIP) power modules
2. Process and integration of multi-die power delivery in package,

with invited speakers from both industries and academics to address the challenges and opportunities in miniaturization and efficiency power delivery that sees increasing application areas. Sessions will consist of presentations followed by active discussions between IC designers, assembling experts and substrate/materials providers **bringing** innovative solutions to address power delivery in package challenges.

Workshop General Chair Professor Hongbin Yu commenting on this workshop's venue: "We are excited to have this workshop in Phoenix area, where there are many microelectronics companies in the Valley area that are very active in developing new semiconductor devices that will require innovation in the scaling of power integration and much-improved efficiency. Through this workshop, we hope to foster much stronger collaboration between academia and industry in this region resulting in new and key contributions in power delivery innovations."

Technical Program Chair Jim Doyle from Dialog Semiconductor points out "The workshop intends to bring together technical experts on SOC packaging mainly from the Phoenix area, the line between pure integration and multichip SIPs have become blurry since processes such as InFo, MCeP, WLP/RCP, WL-esip, 3D TSV offered by different foundries and packaging companies, provide area effective solutions competitive with full integration. This could revolutionize the decision to integrate or not to integrate. Join us to learn more about the options and trade-offs."

Confirmed Invited Speakers	Cian O'Mathuna, <i>Tyndall National University, Ireland</i>	PSIP and PwrSoC: Past and Future
	<i>Intel Corporation, Chandler, AZ</i>	Power Supply in Multi-die Packaging
	Karim Arabi, <i>Atlazo</i>	Low Power Packaging in IoT Applications
	<i>Shinko, Tempe, AZ</i>	Embedded Dies and Passive Integration
	Ian Kent, <i>Dialog Semiconductor, U.S.A.</i>	Power Supply in a Package
	John Pigott, <i>NXP Chandler AZ</i>	Package & Circuit Interactions and Automotive Applications
	Mark Gerber, <i>ASE</i>	New Generation Power Packaging Technology

See the rest of informative program by world-leading technologists at the workshop website.

In addition, student posters are solicited.

Registration is open until October 31st, 2019, and is available through the workshop website.

Sign-up for a Partnership Opportunity by sending email to yuhb@asu.edu, or Jim.Doyle@diasemi.com

Two types of company partnerships are available:

<p>Platinum level provides an exhibit table for the duration of the workshop, two free registrations to all events – plus the Gold-level banner and logo display opportunities.</p>	<p>The Gold level includes company visibility through banner and logo displays shown in workshop events, the technical program and in website and announcement emails. One free registration to all events,</p>
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Host

ASU Arizona State University
National Science Foundation
Efficient Vehicle and Sustainable
Transportation (EVSTS) Center

Sponsors



The workshop will be held at Arizona State University's SkySong Innovation in Scottsdale, AZ. The General Chair is Professor Hongbin Yu from ASU's School of Electrical, Computer and Energy Engineering, who has participated in many of the prior PwrSoC workshops, and the Technical Program Chair for the workshop is Jim Doyle from Dialog Semiconductor, who presented a keynote speech at the PwrSoC2018. The workshop support team includes Arnold Alderman representing PSMA, Francesco Carobolante representing IEEE PELS, and Prof. Hanh-Phuc Le, Dept. of Electrical, Computer, and Energy Engineering, the University of Colorado at Boulder who is currently IEEE PELS Topic 2 Committee Chair.